



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-06-11
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BYOF*0339BJ6	A	SA1A	2013-06-11
Amount	UoM	Unit type	ST ECOPACK Grade	
25.04	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X0.9	14	No lead	
Comment	Package: VFQFPN 3x3x0.9 1.7 16L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BYOF*0339BJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.782	mg		Silicon die	Silicon (Si)	7440-21-3		0.782	mg	1000000	31228
Lead frame	Copper & its alloys	9.808	mg		Alloy	Copper	7440-50-8		9.475	mg	966048	378364
Lead frame					Alloy	Iron	7439-89-6		0.221	mg	22533	8825
Lead frame					Alloy	Phosphorus	7723-14-0		0.002	mg	204	80
Lead frame					Alloy	Zinc	7440-66-6		0.012	mg	1223	479
Lead frame					Alloy	Silver	7440-22-4		0.098	mg	9992	3913
Die attach	Other Organic Materials	0.042	mg		Glue	Silver (Ag)	7440-22-4		0.028	mg	66667	1118
Die attach					Glue	methylene diacrylate	42594-17-2		0.008	mg	190476	319
Die attach					Glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.002	mg	47619	80
Die attach					Glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.002	mg	47619	80
Die attach					Glue	Palladium (Pd)	7440-05-3		0.001	mg	23810	40
Die attach					Glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.001	mg	23810	40
Bonding wire	Precious metals	0.2	mg		Bonding wire	Gold (Au)	7440-57-5		0.2	mg	1000000	7987
Encapsulation	Other Organic Materials	14.1	mg		Molding compound	Silica fused	60676-86-0		13.212	mg	937021	527594
Encapsulation					Molding compound	Epoxy resin	Proprietary		0.423	mg	30000	16892
Encapsulation					Molding compound	Phenol resin	Proprietary		0.423	mg	30000	16892
Encapsulation					Molding compound	Carbon black	1333-86-4		0.042	mg	2979	1677
Finishing	Other inorganic materials	0.11	mg		Connection coating	Sn	7440-31-5		0.11	mg	1000000	4393